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# Vertical Contact Probe Card (VCPC<sup>TM</sup>)

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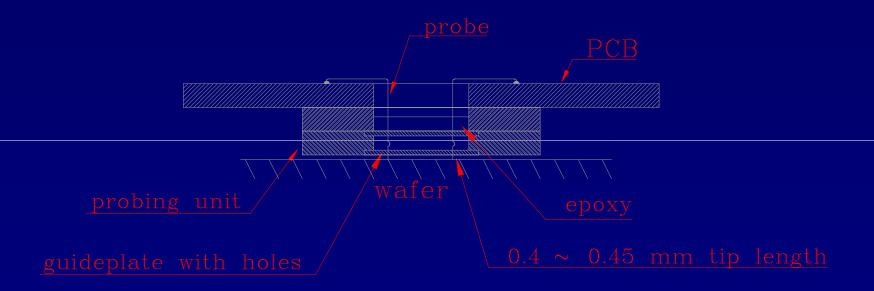
#### Introduction

- Two Types (VCPC and Ribbon VCPC)
- Matrix C4, BGA
- Multi-die memory, Logic

### **Topics of Discussion**

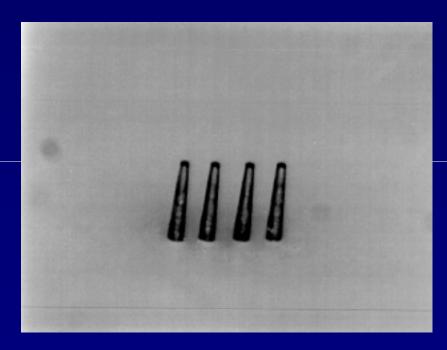
- Concept and Structure
- Mechanical Characteristics
- Electrical Characteristics
- Concept and Structure of Ribbon VCPC

## Concept and Structure

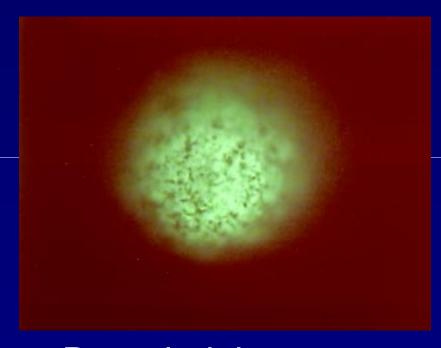


Cross-sectional view of VCPC

### Concept and Structure

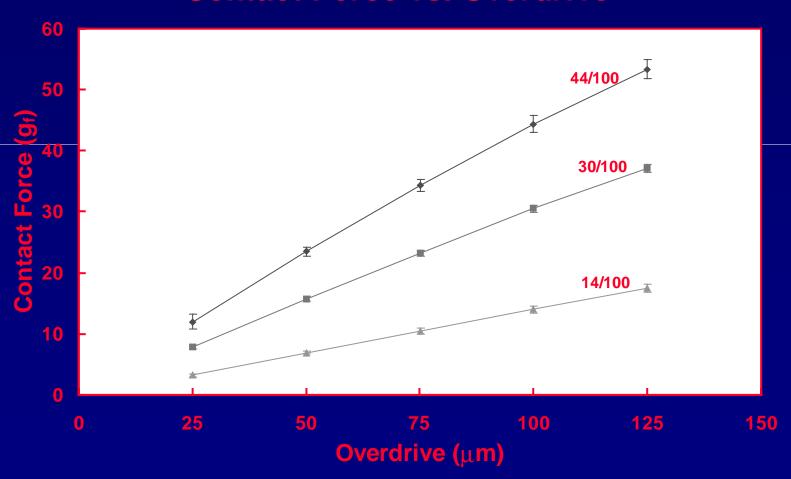


Four probe tips

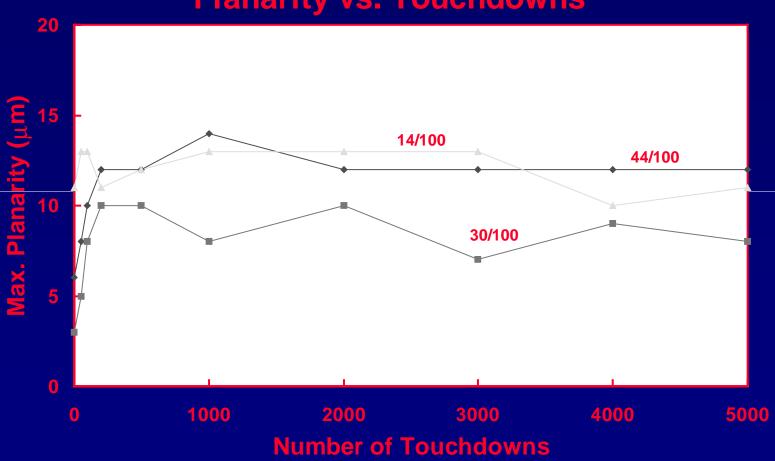


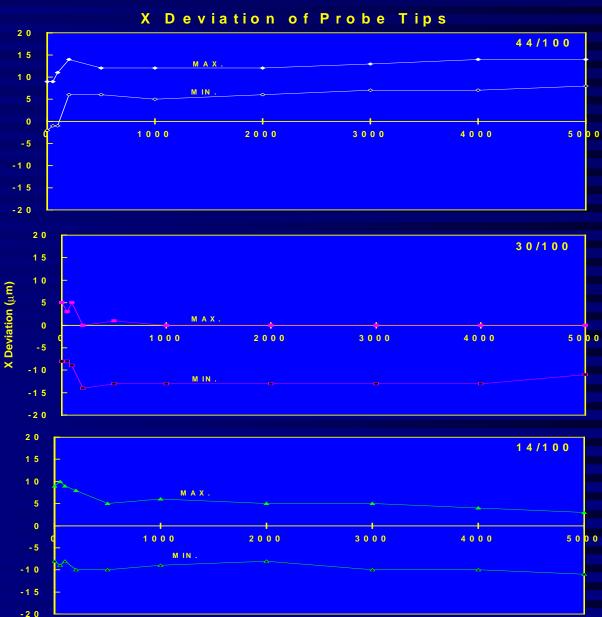
Rounded tip

#### **Contact Force vs. Overdrive**



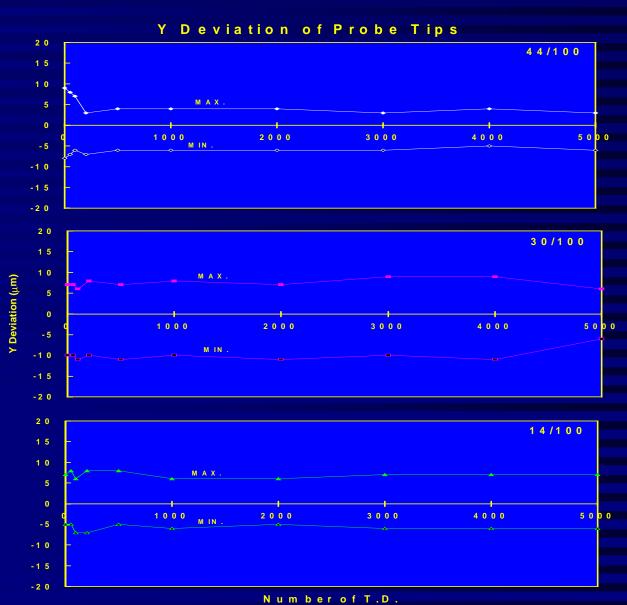








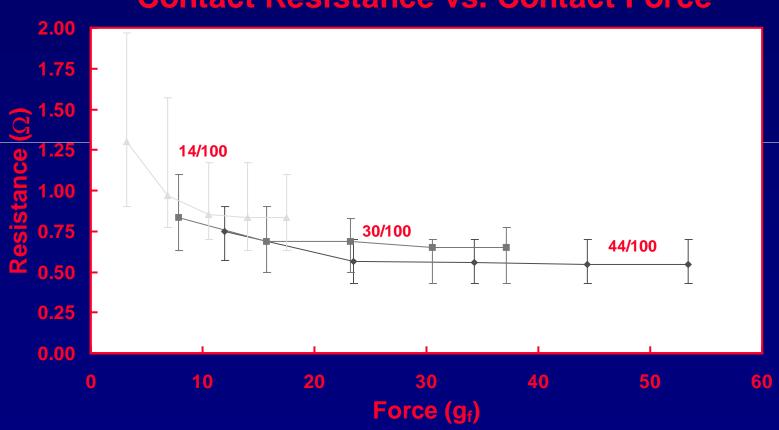
Number of T.D.



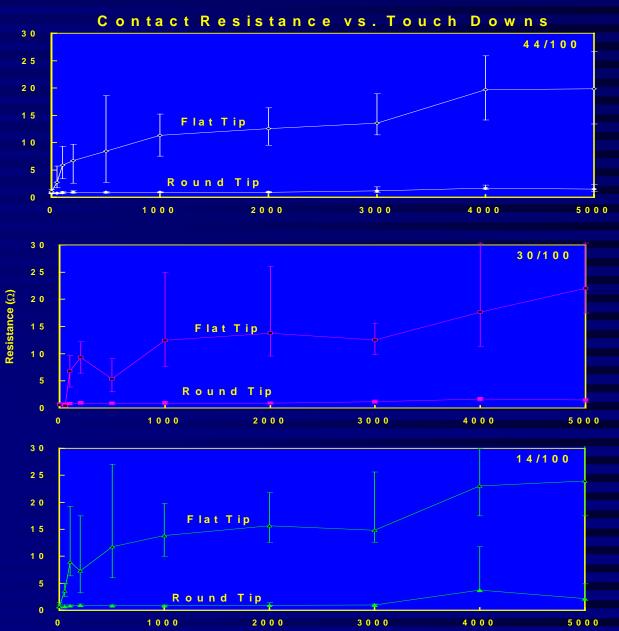


### **Electrical Characteristics**

#### **Contact Resistance vs. Contact Force**



#### **Electrical Characteristics**





## VCPC Specifications

Alignment

Planarity

Minimum Pitch

Probe Material

Probe Diameter

Probe Tip Length

Probe Tip Diameter

Contact Resistance

Contact Force

Maximum Current

Temperature Range

Maximum Device Size

Minimum Board Size

Life

 $\pm 10 \, \mu m$ 

±10 μm

 $135 \mu m$ 

W, Re-W

80 μm

400-450 μm

30 μm

 $1\Omega$  max

 $30 \text{ g} \pm 10\% \text{ @ } 100 \text{ } \mu\text{m O.D.}$ 

250 ma

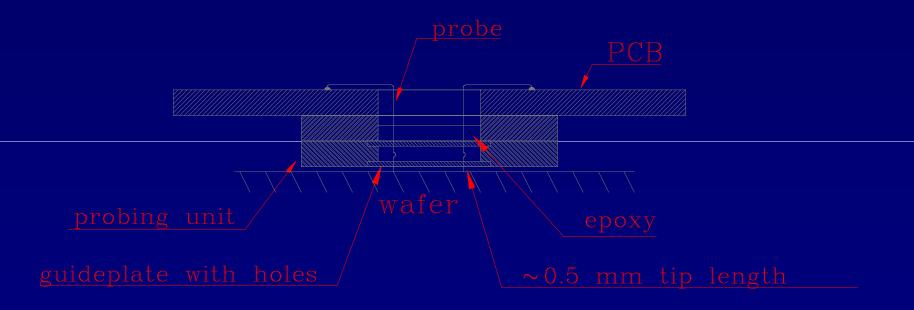
0-125 °C

100 x 100 μm, or 50 x 150 μm

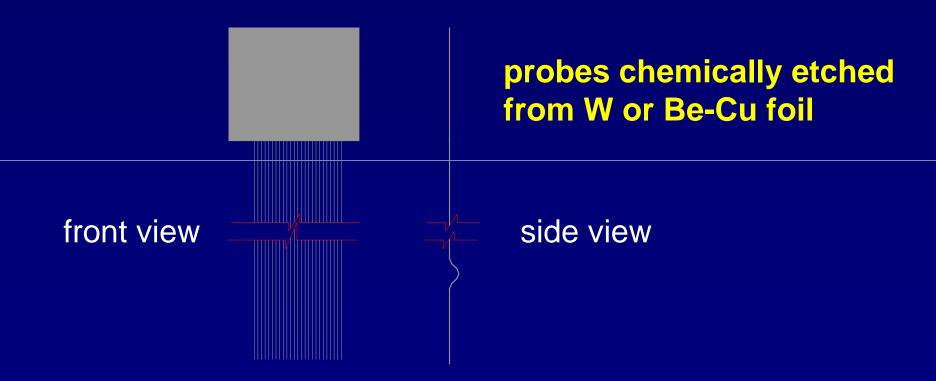
4.5" x 7", or 5.25" diameter

1 million touchdowns max.



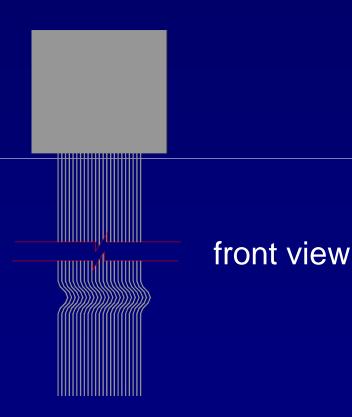


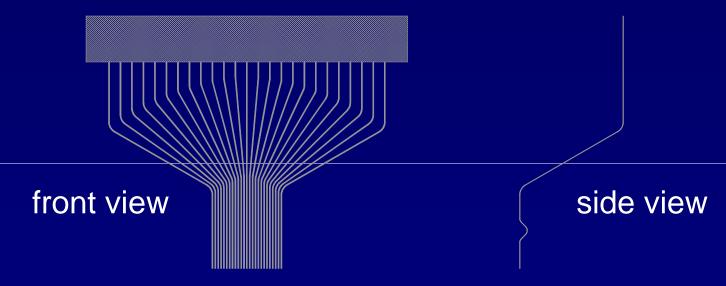
Schematic of Ribbon VCPC



Schematic of ribbon probe grouping

- chemical etching of the bead directly into the probe
- Lateral instability is manageable





- Small-to-large pitch, etched grouping
- Attached to underside of PCB via an interposer

#### **Future Work**

- Mechanical and Electrical Testing of Ribbon VCPC
- Materials Evaluation
- Design for more scrub action